

Number of contacts 10, 14, 16, 20, 26, 34, 40, 50, 60, 64

Contact arrangement straight

Contact length 4.5 mm

Approvals IEC 60603-13

Design acc. to D 2632
BT 224
BS 9525
NFC 93-428 (HE 10)

Pitch 2.54 mm [0.100"]

Working current 1 A

Working voltage 350 V DC or AC peak

Test voltage $U_{r.m.s.}$ 1 kV

Contact resistance $\leq 20 \text{ m}\Omega$
Insulation resistance $\geq 10^9 \Omega$

Temperature range $-55 \text{ }^\circ\text{C} \dots + 125 \text{ }^\circ\text{C}$
The maximum temperature includes heating of contacts and ambient temperature

Materials
Moulding PBT
UL 94-V0
Contacts Phosphor bronze

Contact surface
Contact zone plated according to performance level¹⁾

Terminations Recommended PCB through holes

<i>Tin-lead plated PCB</i>	Hole	$1.15^{+0.025}$
	Cu	min. 25 μm
	Sn	max. 15 μm
	Plated hole	0.94-1.09 mm
<i>Chemical tin-plated PCB</i>	Hole	$1.15^{+0.025}$
	Cu	min. 25 μm
	Sn	min. 0.8 μm
	Plated hole	1.00-1.10 mm
<i>Au / Ni plated PCB</i>	Hole	$1.15^{+0.025}$
	Cu	min. 25 μm
	Ni	3-7 μm
	Au	0.05-0.12 μm
	Plated hole	1.00-1.10 mm
<i>Silver plated PCB</i>	Hole	$1.15^{+0.025}$
	Cu	min. 25 μm
	Ag	0.1-0.3 μm
	Plated hole	1.00-1.10 mm
<i>OSP copper plated PCB</i>	Hole	$1.15^{+0.025}$
	Cu	min. 25 μm
	Plated hole	1.00-1.10 mm
PCB board thickness: $\geq 1.6 \text{ mm}$		

Insertion and withdrawal forces

Number of contacts	Maximum force [N]
	Performance level 1
10	20
14	28
16	32
20	40
26	52
34	68
40	80
50	100
60	120
64	128

¹⁾ Performance level 1 as per IEC 60603-13, ≥ 500 mating cycles, 10 days gas test